

NOTES:

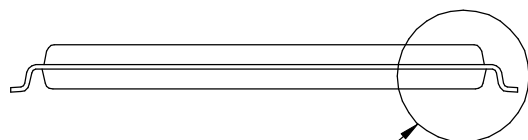
1. ALL DIMENSIONS ARE IN MILLIMETERS.

2. DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL AND MUST BE LOCATED WITHIN ZONE INDICATED.

3. DIMENSIONS D1 AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.

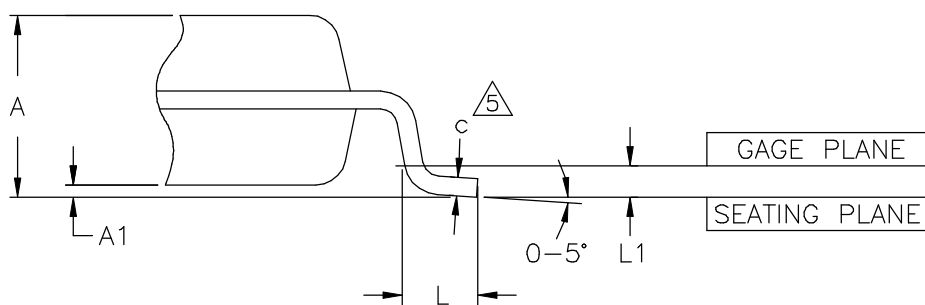
4. LEAD DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR FOOT.

5. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 mm AND 0.25 mm FROM THE LEAD TIP.




SEE DETAIL A

DIM	MIN	MAX
A	—	1.24
A1	0.05	0.20
—	—	—
b	0.15	0.27
c	0.10	0.21
D	19.50	20.50
D1	18.20	18.60
E	7.80	8.20
e	0.50 BSC	
L	0.50	0.70
L1	0.25 BSC	



DETAIL A

SIGNATURE		DATE		 Dallas Semiconductor			
DOC. CONTROL:							
ENGR. MGR:				MARKETING OUTLINE 32 LD. TSOP(1), 8 X 20 MM			
MFG. ENGR:							
CHECKED BY:							
DRAWN BY:				SIZE A	FSCM NO.	PART NO.	REV A
DO NOT SCALE DWG.				SCALE N/A		SHEET 1 OF 1	